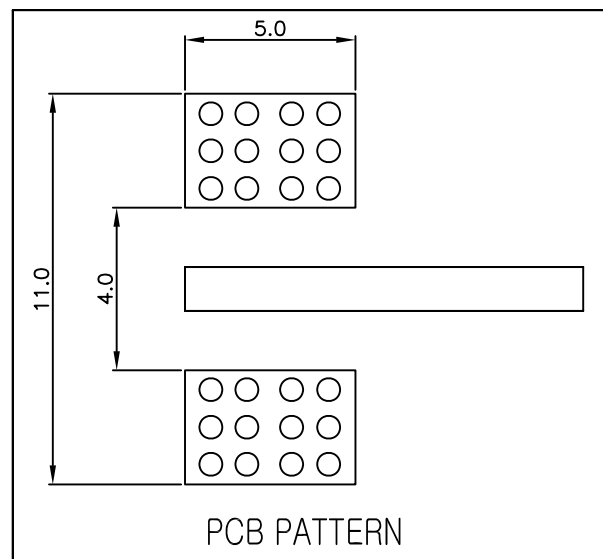
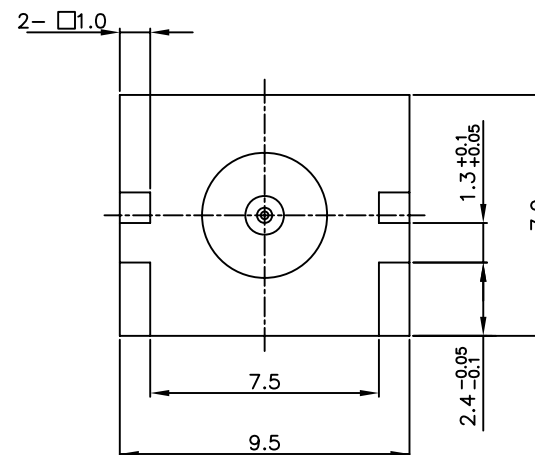
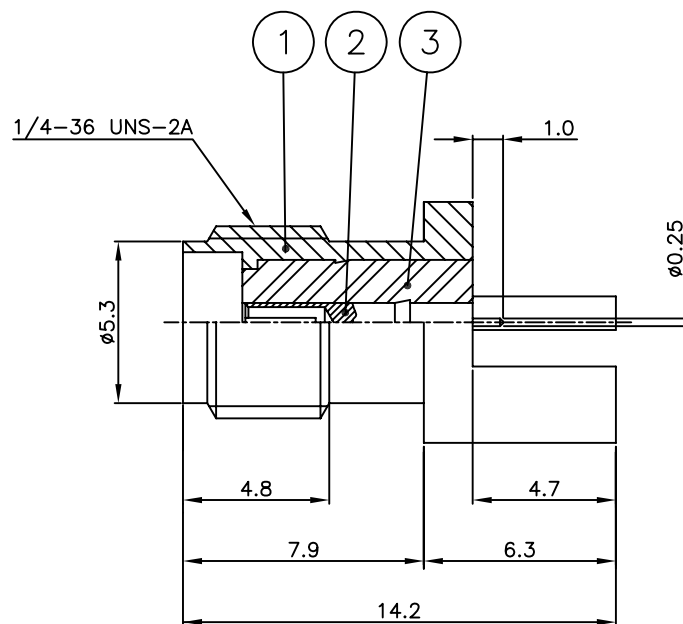
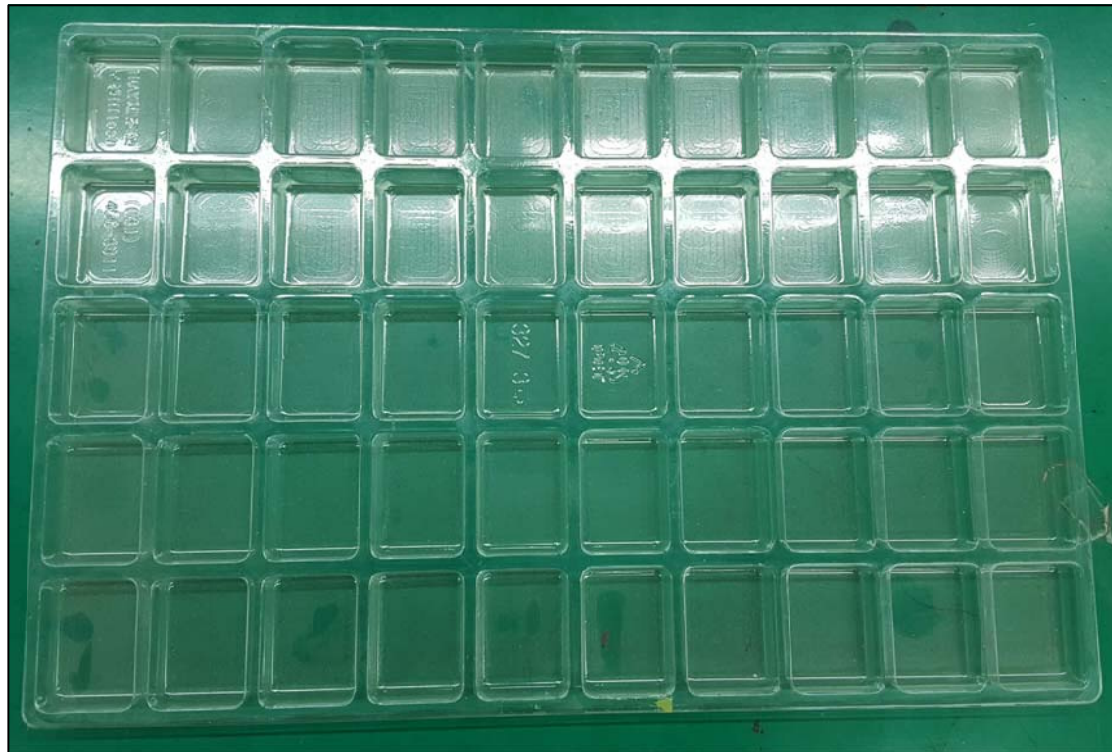


포장사양 2페이지 참조



3	INSULATOR	1	TEFLON		DIN02177-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03643-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD03282-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 02. 04.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017				
	Angle	APPROVED BY I.C.KIM							
MATERIAL	±1°	CHECKED BY H.J.LEE			TITLE SMA50 PCB JS-4R (edge)				
		DRAWN BY C.K.KIM							
FINISH		SCALE 4/1	UNIT mm		A4	DWG NO. CN02066-7/4	REVISION I R		SHEET 1 of 1



CN02066 포장 사양

1. 부광하이텍 327-3호 (PET) Tray 사용
2. Tray 개당 제품 2ea씩 포장하여
Total 100ea 포장